

DA3X101K

Silicon epitaxial planar type

For high speed switching circuits
DA2J101 in Mini3 package

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Halogen-free / RoHS compliant
(EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 21

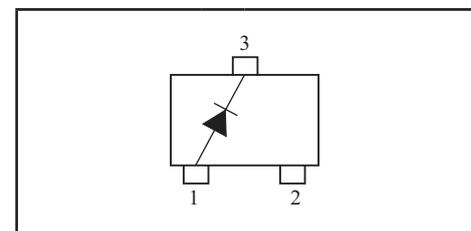
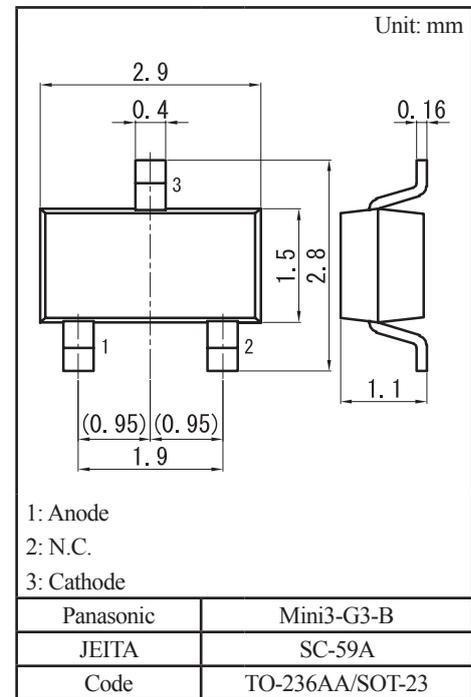
■ Packaging

DA3X101K0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter | Symbol | Rating | Unit |
|--|-----------|-------------|------------------|
| Reverse voltage | V_R | 80 | V |
| Maximum peak reverse voltage | V_{RM} | 80 | V |
| Forward current | I_F | 100 | mA |
| Peak forward current | I_{FM} | 225 | mA |
| Non-repetitive peak forward surge current *1 | I_{FSM} | 500 | mA |
| Junction temperature | T_j | 150 | $^\circ\text{C}$ |
| Storage temperature | T_{stg} | -55 to +150 | $^\circ\text{C}$ |

Note) *1: $t = 1 \text{ s}$

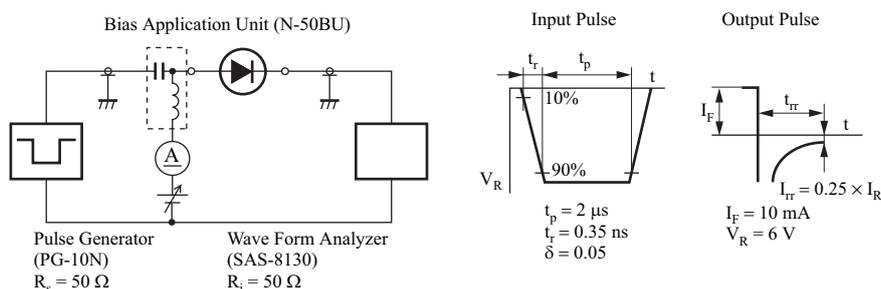


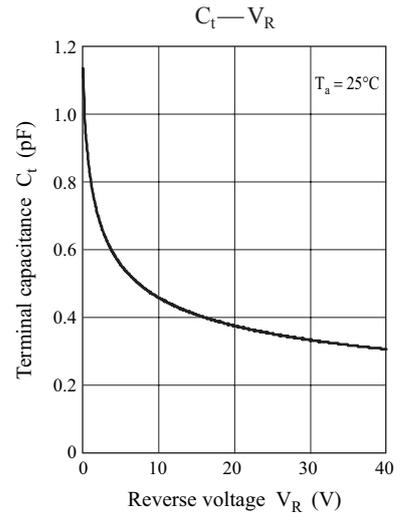
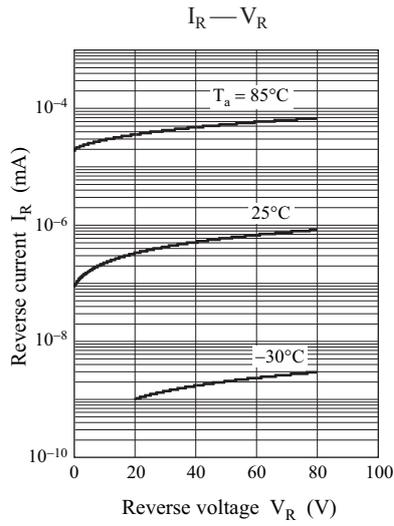
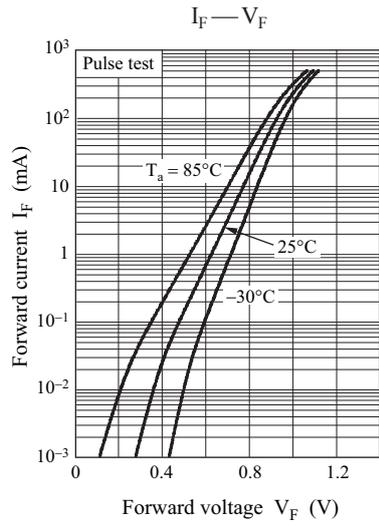
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter | Symbol | Conditions | Min | Typ | Max | Unit |
|--------------------------|----------|--|-----|------|------|------|
| Forward voltage | V_F | $I_F = 100 \text{ mA}$ | | 0.92 | 1.20 | V |
| Reverse voltage | V_R | $I_R = 100 \mu\text{A}$ | 80 | | | V |
| Reverse current | I_R | $V_R = 80 \text{ V}$ | | | 100 | nA |
| Terminal capacitance | C_t | $V_R = 0 \text{ V}, f = 1 \text{ MHz}$ | | | 1.2 | pF |
| Reverse recovery time *1 | t_{rr} | $I_F = 10 \text{ mA}, V_R = 6 \text{ V}, I_{rr} = 0.25 \times I_R$ | | | 3 | ns |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

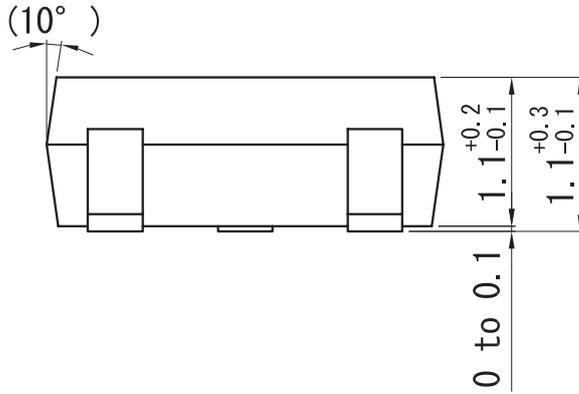
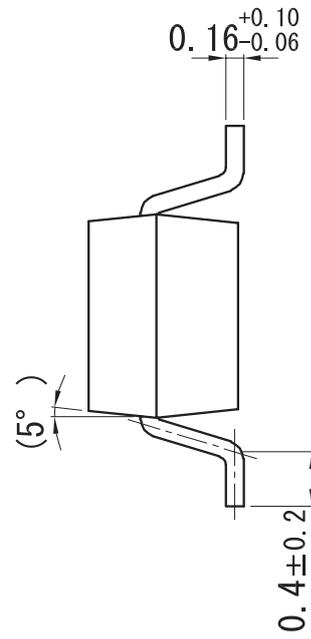
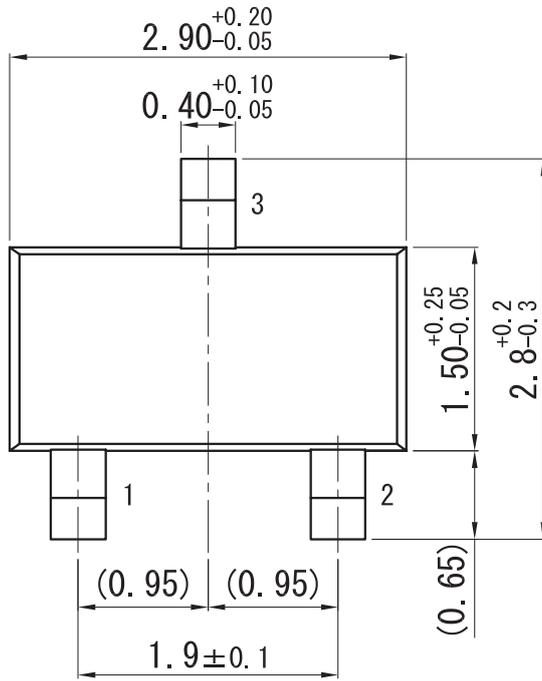
2. Absolute frequency of input and output is 100 MHz
3. *1: t_{rr} measurement circuit



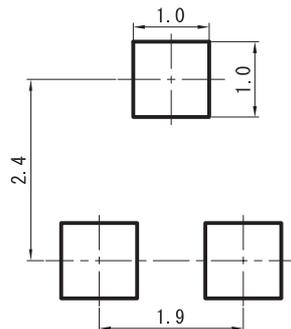


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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